

Halogenfree FR4

Laminate: **R-1566W**

Prepreg: **R-1551W**

Standard size warp weft mm	Copper foil thickness	Laminate thickness	Thickness tolerance
920 x 1220			
1160 x 1060		Thin laminates (excluding Copper foil thickness)	according to IPC - 4101 B B - (C)
1060 x 1220	0,018 mm		
1110 x 1220			
1060 x 1280	0,035 mm	-----	
(1840 x 1230)	0,070 mm		
(2150 x 1160)		Rigid laminates (including Copper foil thickness)	according to IPC - 4101 B L - (M)
(2150 x 1280)			
(2150 x 1220)			



Other thicknesses on request

[Features]

- ▶ Halogenfree FR4 material for PCB production
- ▶ A flame-retarding level of UL94 V0 achieved without using halogen flame-retarding agents.
- ▶ Tg: medium Tg class
- ▶ Excellent through-hole conductive reliability, excellent heat resistance
- ▶ Excellent CAF resistance
- ▶ Tracking resistance CTI 500
- ▶ For lead free assembly
- ▶ Conforms to the most international standards:
IPC-4101B/92, UL94, IPC 4562, UL 946
- ▶ Clear prepreg available
- ▶ UV-blocking: R-1566W / R-1551W with UV-blocking characteristic (W = internal suffix)
- ▶ Workability: With standard FR4 process

[Applications]

PCs, computer peripherals, cellular phones, digital video cameras, automotive etc